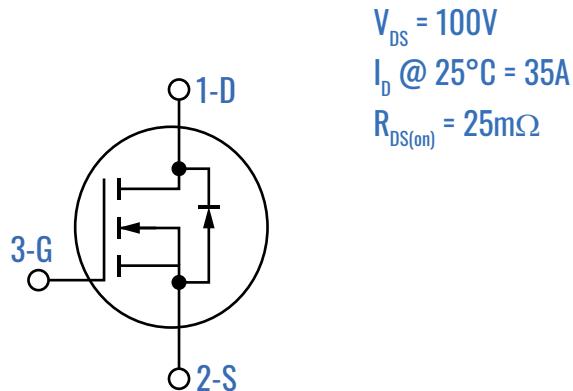


KEY FEATURES

- LOW THERMAL RESISTANCE
- OPTIMIZED FOR FAST SWITCHING
- TO-258 OR TO-254 3L PACKAGE
- HERMETICALLY SEALED, ISOLATED PACKAGE
- JANTX, JANTXV SCREENING AVAILABLE

APPLICATIONS

- SWITCH-MODE AND RESONANT-MODE POWER SUPPLIES
- DC-DC CONVERTERS
- PFC CIRCUITS
- AC AND DC MOTOR DRIVES
- ROBOTICS AND SERVO CONTROLS



ORDERING GUIDE

Part Number	SD11461-1	TO-258
	SD11461-2	TO-254
Description	100V N-Channel Power MOSFET	

ABSOLUTE MAXIMUM RATINGS ($T_c = 25^\circ C$)

SYMBOL	CHARACTERISTIC	TEST CONDITIONS	VALUE	UNIT
$V_{DS,max}$	Drain-Source Voltage		100	V
$V_{GS,max}$	Gate-Source Voltage		-20/+20	V
I_D	Continuous Drain Current		35	A
P_D	Maximum Power Dissipation		147	W
T_J, T_{STG}	Junction Temperature, Operating and Storage		-55 to +150	°C
Θ_{JC}	Thermal Resistance, junction-to-case		0.85	°C/W
T_L	Lead Temperature	soldering, 10s	+300	°C

ELECTRICAL CHARACTERISTICS ($T_c = 25^\circ\text{C}$)

SYMBOL	CHARACTERISTIC	TEST CONDITIONS	MIN.	TYP.	MAX.	UNIT
$V_{(\text{BR})\text{DS}}$	Drain-Source Breakdown Voltage	$V_{GS} < 0\text{V}, I_D = 4\text{mA}$	100			V
$V_{GS(\text{th})}$	Gate Threshold Voltage	$V_{DS} = V_{GS}, I_D = 4\text{mA}$	2.0		4.0	V
I_{DS}	Off-State Drain Current	$V_{GS} = 0\text{V}, V_{DS} = 100\text{V}, T_j = 25^\circ\text{C}$			5.0	μA
		$V_{GS} = 0\text{V}, V_{DS} = 80\text{V}, T_j = 125^\circ\text{C}$			50.0	
I_{GSS}	Gate-Source Leakage Current	$V_{GS} = \pm 20\text{V}, V_{DS} = 0\text{V}$			± 100	nA
$R_{\text{DS(on)}}$	Drain-Source On-state Resistance	$V_{GS} = 10\text{V}, I_D = 30\text{A}, T_j = 25^\circ\text{C}$		20	25	$\text{m}\Omega$
		$V_{GS} = 10\text{V}, I_D = 30\text{A}, T_j = 125^\circ\text{C}$		33	40	
g_{fs}	Transconductance	$V_{DS} = 15\text{V}, I_D = 30\text{A}$	18			S
C_{iss}	Input Capacitance	$V_{GS} = 0\text{V}, V_{DS} = 25\text{V}, f = 1\text{MHz}$		4300		pF
C_{oss}	Output Capacitance			450		pF
C_{rss}	Reverse Transfer Capacitance			175		pF
$t_{\text{d(on)}}$	Turn-On Delay	$V_{GS} = 10\text{V}, V_{DD} = 50\text{V}, I_D = 50\text{A}, R_g = 2.5\Omega$ external		15		ns
t_r	Rise Time			12		ns
$t_{\text{d(off)}}$	Turn-Off Delay			47		ns
t_f	Fall Time			12		ns
Q_g	Total Gate Charge	$V_{GS} = 10\text{V}, V_{DS} = 80\text{V}, I_D = 30\text{A}$		87		nC

SOURCE-DRAIN DIODE RATINGS ($T_c = 25^\circ\text{C}$)

SYMBOL	CHARACTERISTIC	TEST CONDITIONS	MIN.	TYP.	MAX.	UNIT
I_s	Continuous Source Current				35	A
I_{sm}	Pulsed Source Current	PW limited by T_j			100	A
V_{sd}	Diode Forward Voltage	$V_{GS} = 0\text{V}, I_D = 30\text{A}$		1	1.5	V
t_{rr}	Reverse Recovery	$I_D = 10\text{A}, di/dt = 100\text{A}/\mu\text{s}$		89	120	ns

PERFORMANCE CHARACTERISTICS

Fig 1: Case Temperature vs. Power Dissipation

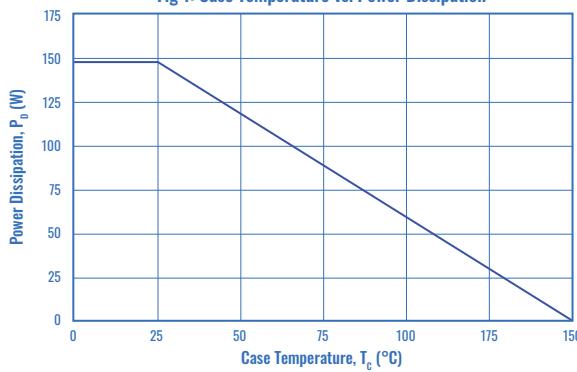
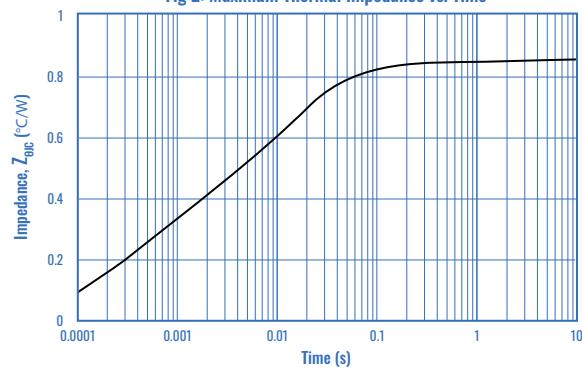


Fig 2: Maximum Thermal Impedance vs. Time



PERFORMANCE CHARACTERISTICS (cont.)

Fig 3: On-Resistance vs. Junction Temperature

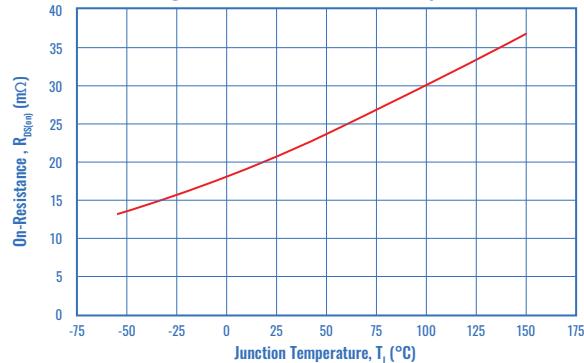


Fig 4: On-Resistance vs. Drain Current

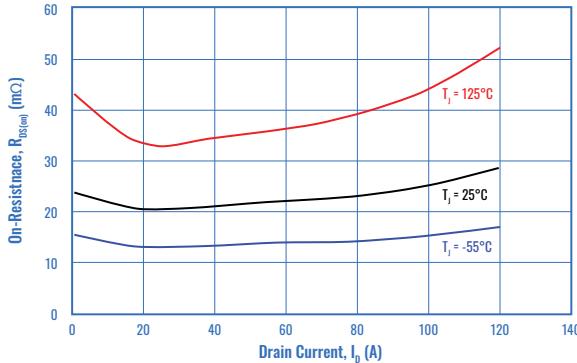


Fig 5: Drain-Source Voltage vs. Drain Current

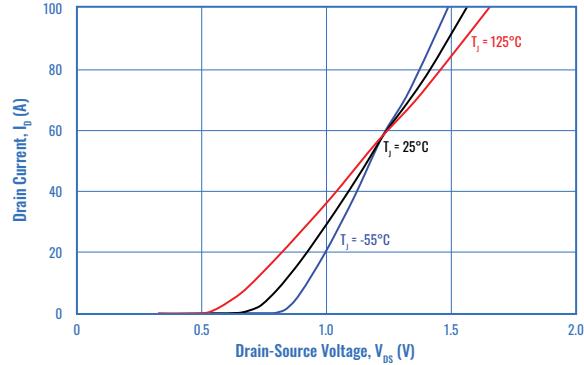
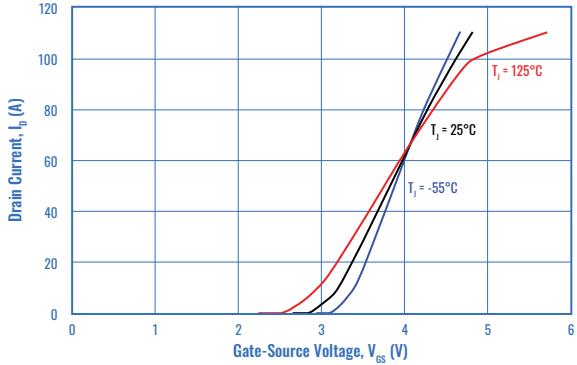
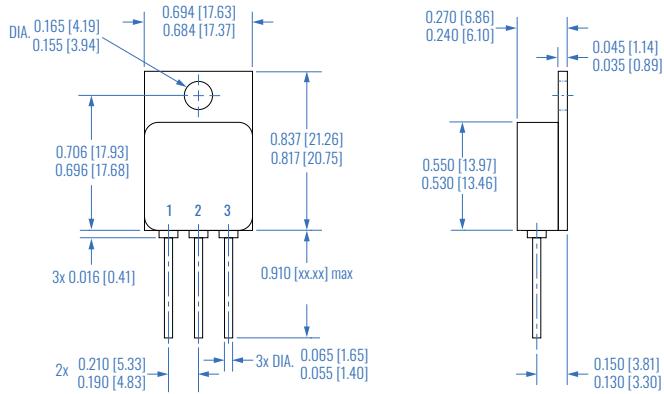


Fig 6: Gate-Source Voltage vs. Drain Current

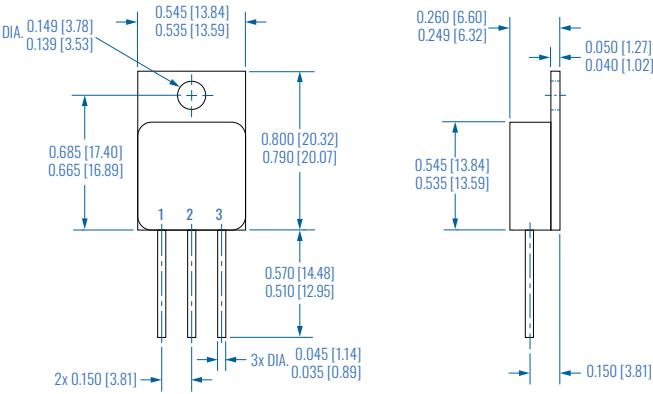


OUTLINE DIMENSIONS

TO-258



TO-254



Also available with 90° lead bend, consult factory
All Dimensions are in Inches (mm)